

Part Number: XZM2DG55W-3

3.2x1.6mm SMD CHIP LED LAMP

Features

- Ideal for indication light on hand held products
- Long life and robust package
- Variety of lens types and color choices available
- Package: 2000 pcs / reel
- \bullet Moisture sensitivity level : level 3
- RoHS compliant

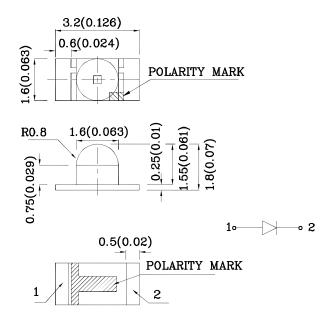






ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Package Schematics



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T_A =25°C)		M2DG (InGaN)	Unit	
Reverse Voltage	$V_{\rm R}$	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	100	mA	
Power Dissipation	P_{D}	120	mW	
Operating Temperature	T_{A}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85	C	
Electrostatic Discharge Threshold (HBM)		450	V	

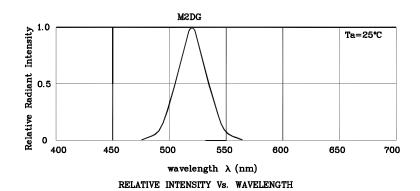
Operating Characteristics (T _A =25°C)		M2DG (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	3.2	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	4	V
Reverse Current (Max.) $(V_R=5V)$	I_R	50	uA
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λР	520	nm
Wavelength of Dominant Emission (Typ.) (I _F =20mA)	λD	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$\triangle \lambda$	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	100	pF

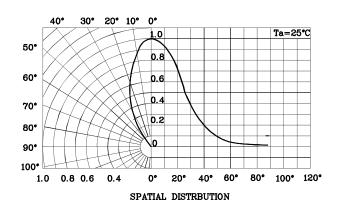
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} {\rm Luminous} \\ {\rm Intensity} \\ {\rm (I_F=20mA)} \\ {\rm mcd} \end{array}$		Wavelength nm λΡ	Viewing Angle 20 1/2
				min.	typ.		
XZM2DG55W-3	Green	InGaN	Water Clear	3100	4190	520	50°

Apr 18,2011 XDSB3586 V3 Layout: Maggie L.

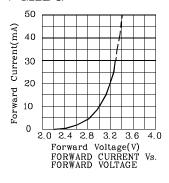


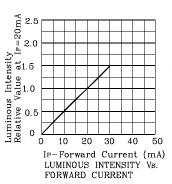


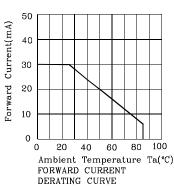


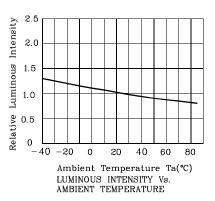


❖ M2DG



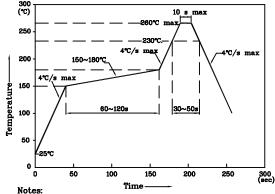






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)



- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

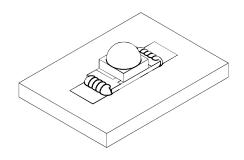
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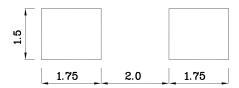


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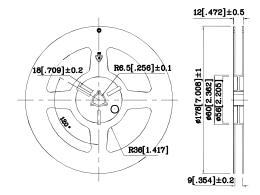
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



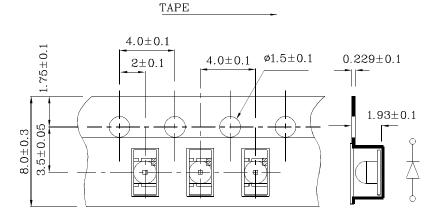
♦ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Reel Dimension



* Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: \pm -0.1V

Note: Accuracy may depend on the sorting parameters.

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PACKING & LABEL SPECIFICATIONS

www.SunLEDusa.com

